

OL-PCF2113x

Wire bond die; 112 bonding pads

10 February 2016

Package information

1. Package summary

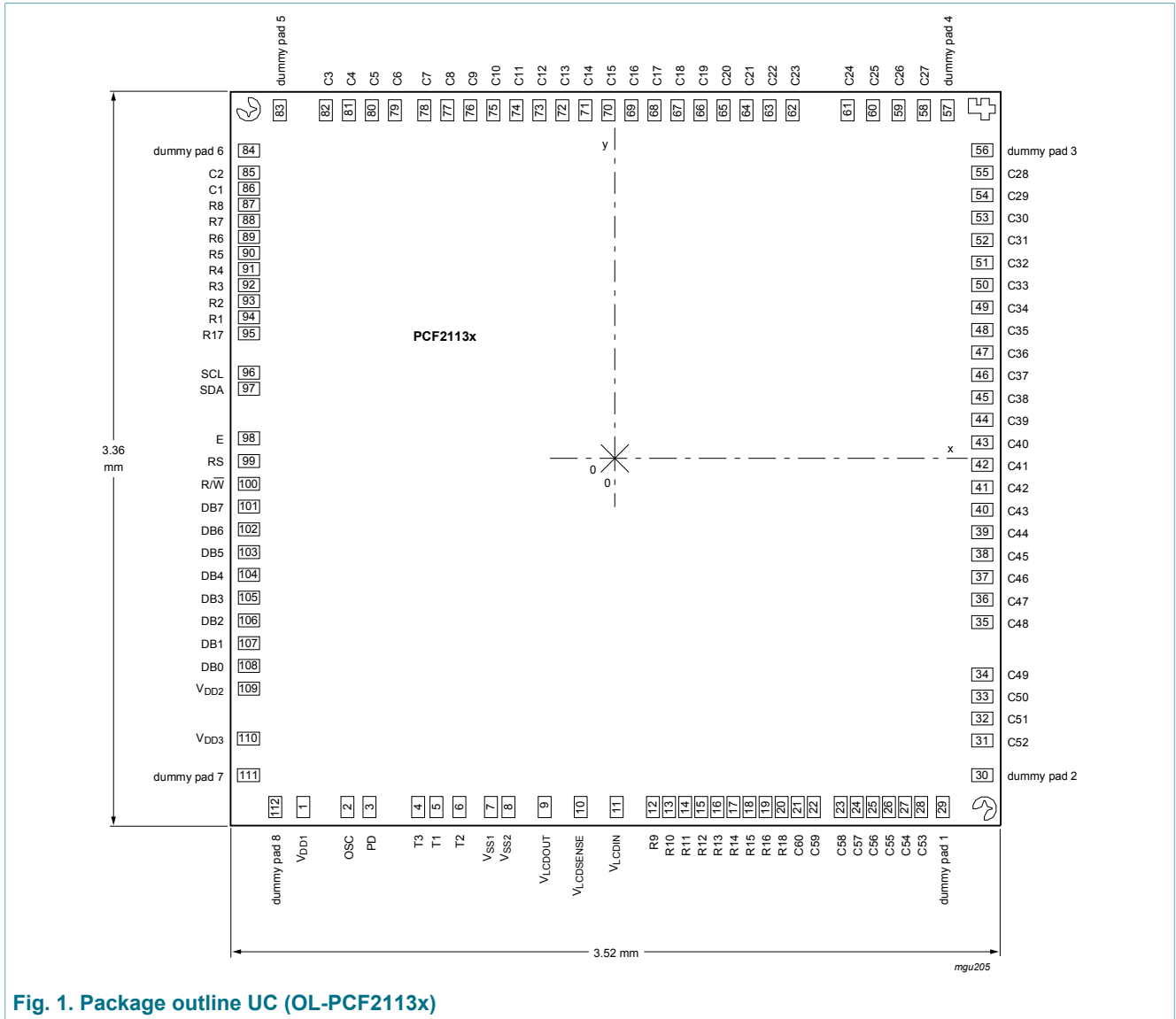
| | |
|---------------------------------------|---------------------|
| Terminal position code | U (upper) |
| Package type descriptive code | UC |
| Package type industry code | UC |
| Package style descriptive code | UC (uncased chip) |
| Package style suffix code | NA (not applicable) |
| Package body material type | X (other) |
| Mounting method type | S (surface mount) |
| Issue date | 13-12-2011 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|------|-----|------|
| D | package length | - | - | 3.36 | - | mm |
| E | package width | - | - | 3.52 | - | mm |
| n ₂ | actual quantity of termination | - | - | 112 | - | |



2. Package outline



3. Legal information

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4. Contents

| | |
|---------------------------|---|
| 1. Package summary..... | 1 |
| 2. Package outline..... | 2 |
| 3. Legal information..... | 3 |

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